

General Description

The G15N10C combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for power switching application and LED backlighting.

Features

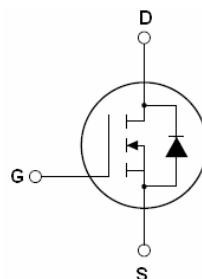
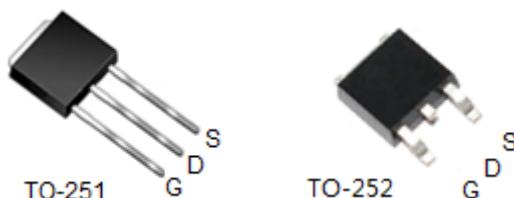
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VDSS	RDS(ON) @10V (typ)	ID
100V	70mΩ	15A

- Ultra Low On-Resistance
- High UIS and UIS 100% Test
- RoHS Compliant

Application

- Power switching application
- LED backlighting

**Schematic Diagram****Ordering Information**

Part Number	Marking	Case	Packaging
G15N10C	G15N10C	TO-251	72pcs/Tube
G15N10C	G15N10C	TO-252	2500pcs/Reel

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	100	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D (DC)	Drain Current (DC) at $T_c=25^\circ C$	15	A
I_D (DC)	Drain Current (DC) at $T_c=100^\circ C$	8.5	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed ^(Note 1)	56	A
P_D	Maximum Power Dissipation($T_c=25^\circ C$)	28	W
E_{AS}	Single Pulse Avalanche Energy ^(Note 2)	16	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	°C

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. E_{AS} condition: $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25 \Omega$

Table 2. Thermal Characteristic

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.3	°C/W

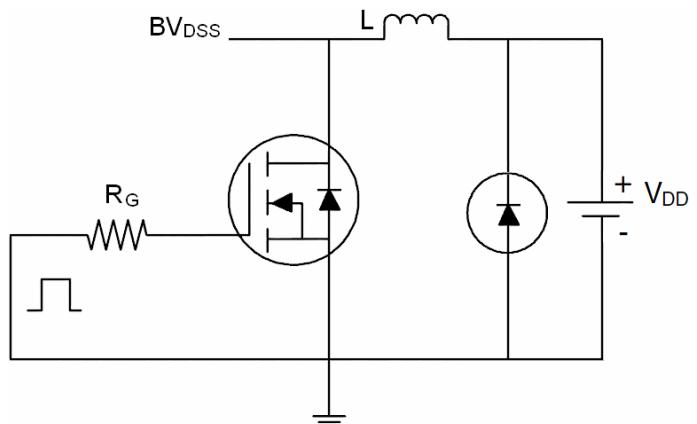
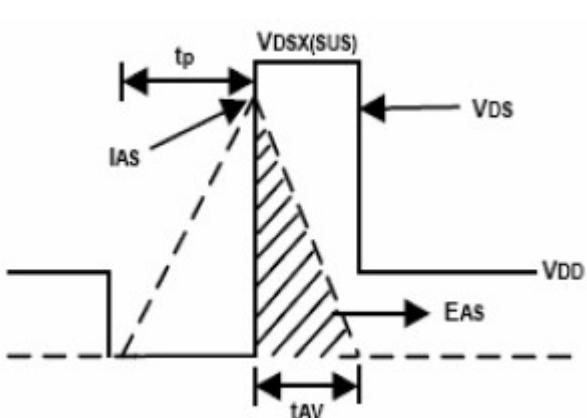
Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100			V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ C$)	$V_{DS}=100V, V_{GS}=0V$			1	μA
I_{DSR}	Zero Gate Voltage Drain Current($T_c=100^\circ C$)	$V_{DS}=100V, V_{GS}=0V$			5	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.5	2.0	2.6	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=4.5A$		70	85	$m\Omega$
Dynamic Characteristics						
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=4.5A$	5			S
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V$ $f=1.0MHz$		612		PF
C_{oss}	Output Capacitance			120		PF
C_{rss}	Reverse Transfer Capacitance			91		PF
Q_g	Total Gate Charge	$V_{DS}=50V, I_D=4.5A$ $V_{GS}=10V$		11		nC
Q_{gs}	Gate-Source Charge			1.9		nC
Q_{gd}	Gate-Drain Charge			2.8		nC
Switching Times						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50V, R_L=8.6\Omega$ $V_{GS}=10V, R_G=3\Omega$		8		nS
t_r	Turn-on Rise Time			3		nS
$t_{d(off)}$	Turn-Off Delay Time			17		nS
t_f	Turn-Off Fall Time			4.5		nS
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current(Body Diode)			14		A
I_{SDM}	Pulsed Source-Drain Current(Body Diode)			56		A
V_{SD}	Forward On Voltage ^(Note 1)	$T_J=25^\circ C, I_{SD}=1A, V_{GS}=0V$		0.74	1	V
t_{rr}	Reverse Recovery Time ^(Note 1)	$T_J=25^\circ C, I_F=4.5A$ $di/dt=500A/\mu s$		21		nS
Q_{rr}	Reverse Recovery Charge ^(Note 1)			97		nC
t_{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible(turn-on is dominated by L_S+L_D)				

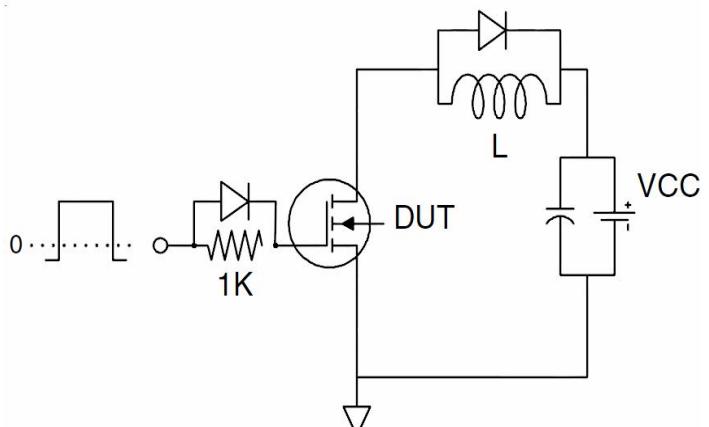
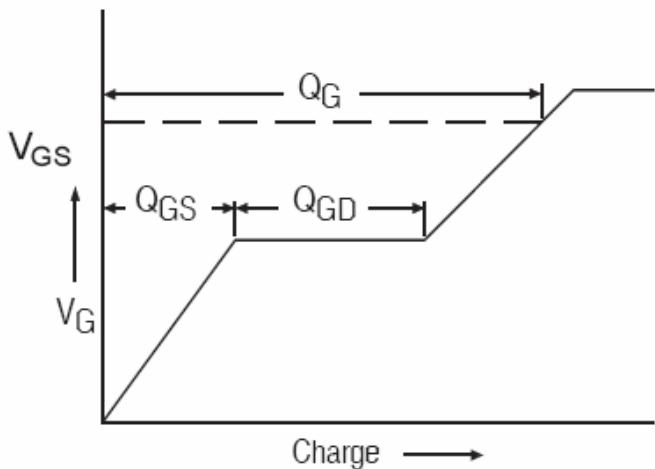
Notes 1.Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 1.5%, Starting $T_J=25^\circ C$

Test Circuit

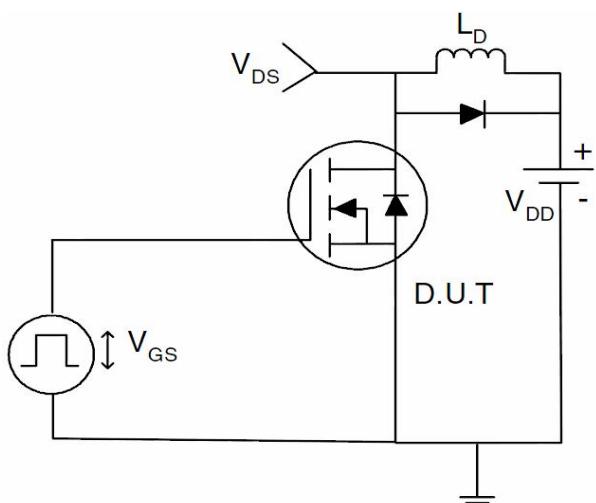
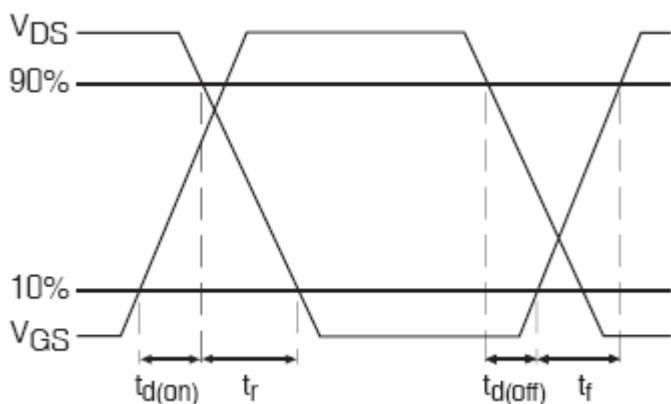
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. On-Region Characteristics

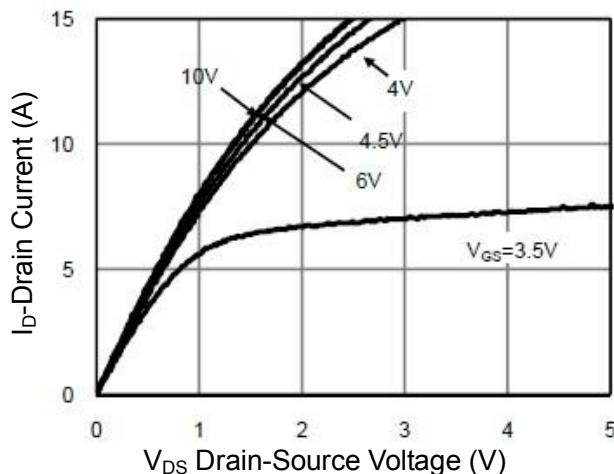


Figure 2: Transfer Characteristics

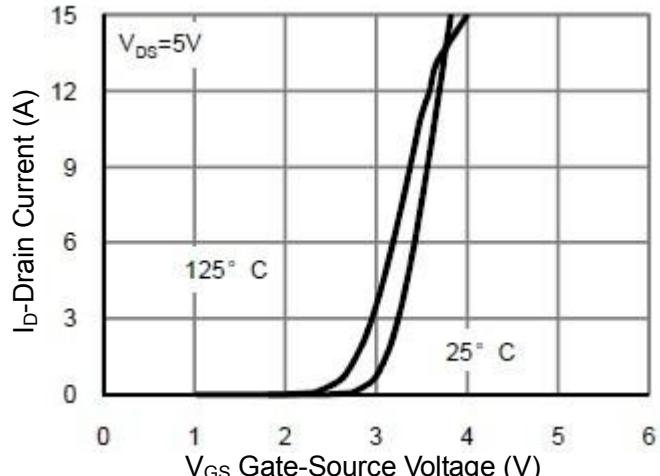


Figure3. On-Resistance vs. Drain Current and Gate Voltage

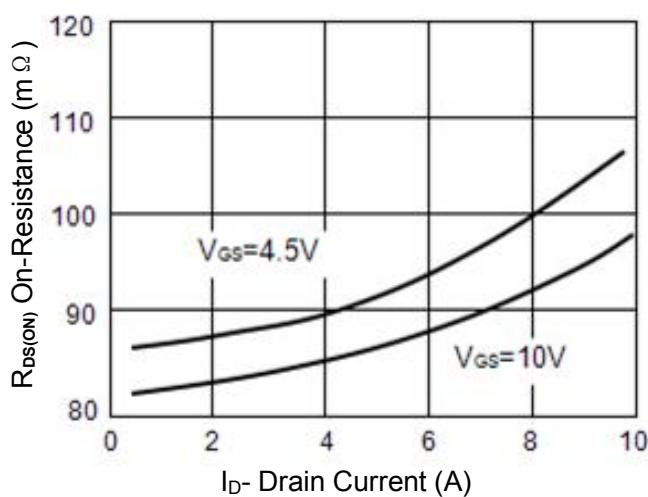


Figure4. On-Resistance vs. Junction Temperature

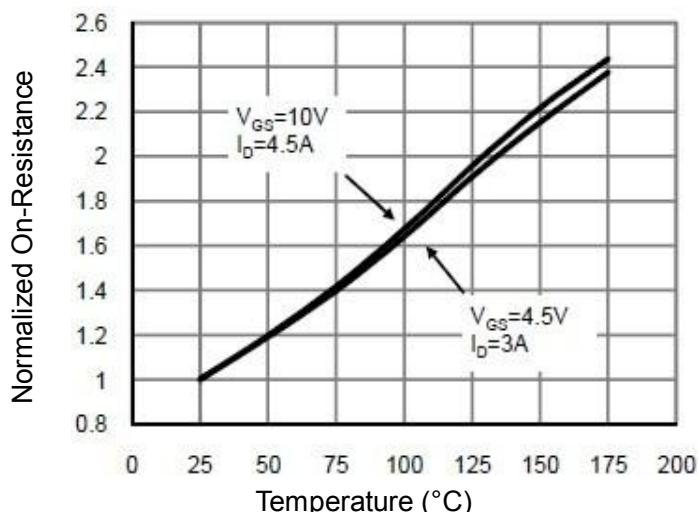


Figure5. On-Resistance vs. Gate-Source Voltage

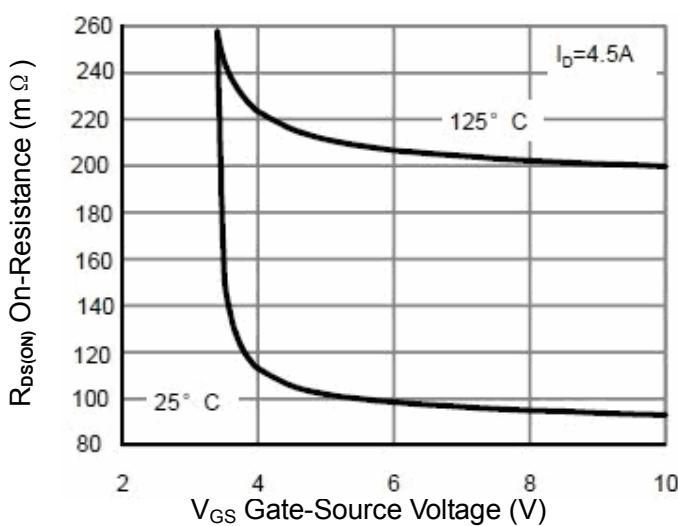


Figure6. Body-Diode Characteristics

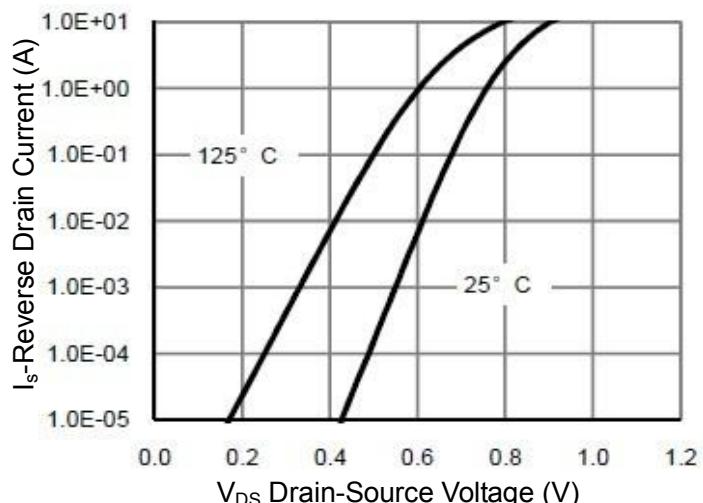


Figure 7. Gate-Charge Characteristics

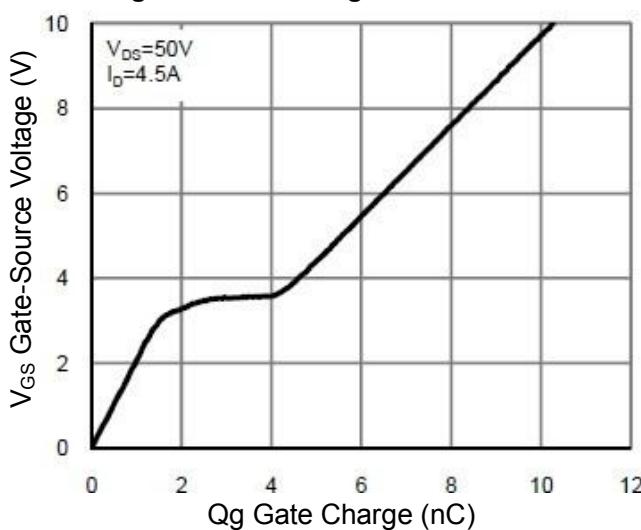


Figure 8. Capacitance Characteristics

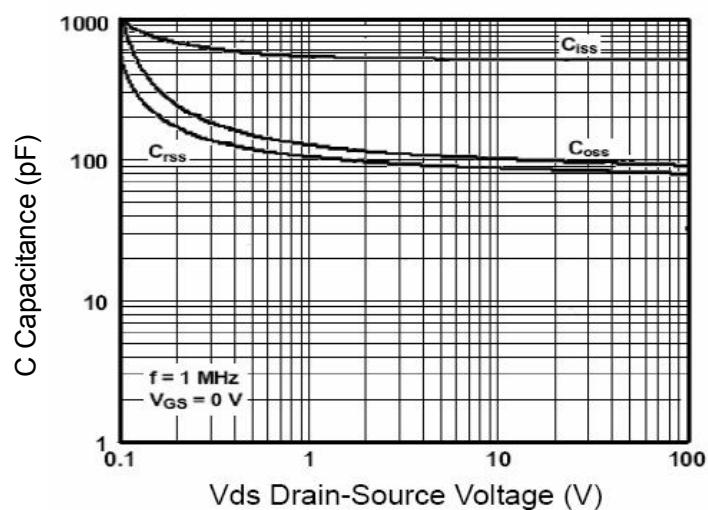


Figure 9. Maximum Forward Biased Safe Operating Area

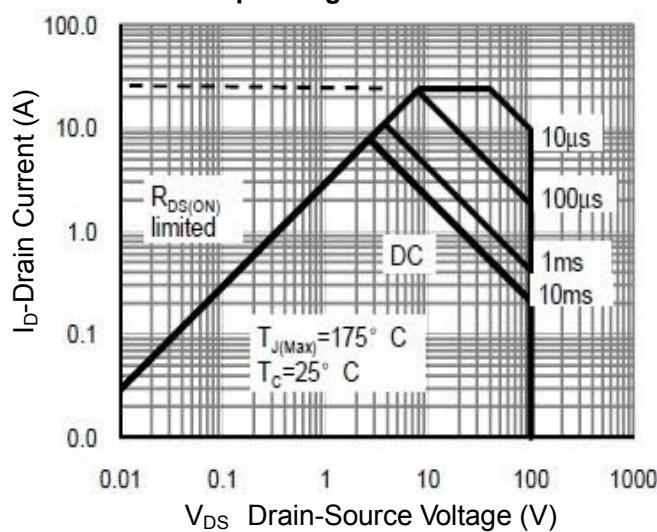


Figure 10. Single Pulse Power Rating Junction-to-Case

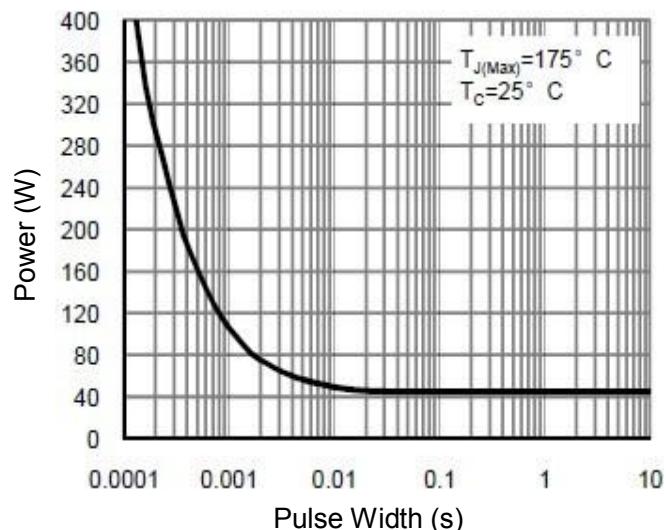
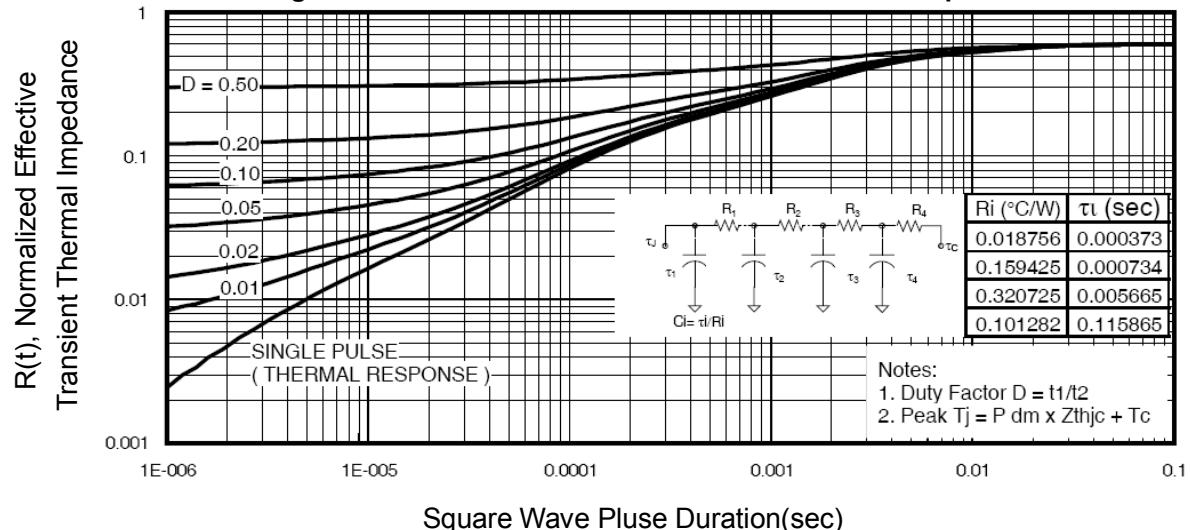
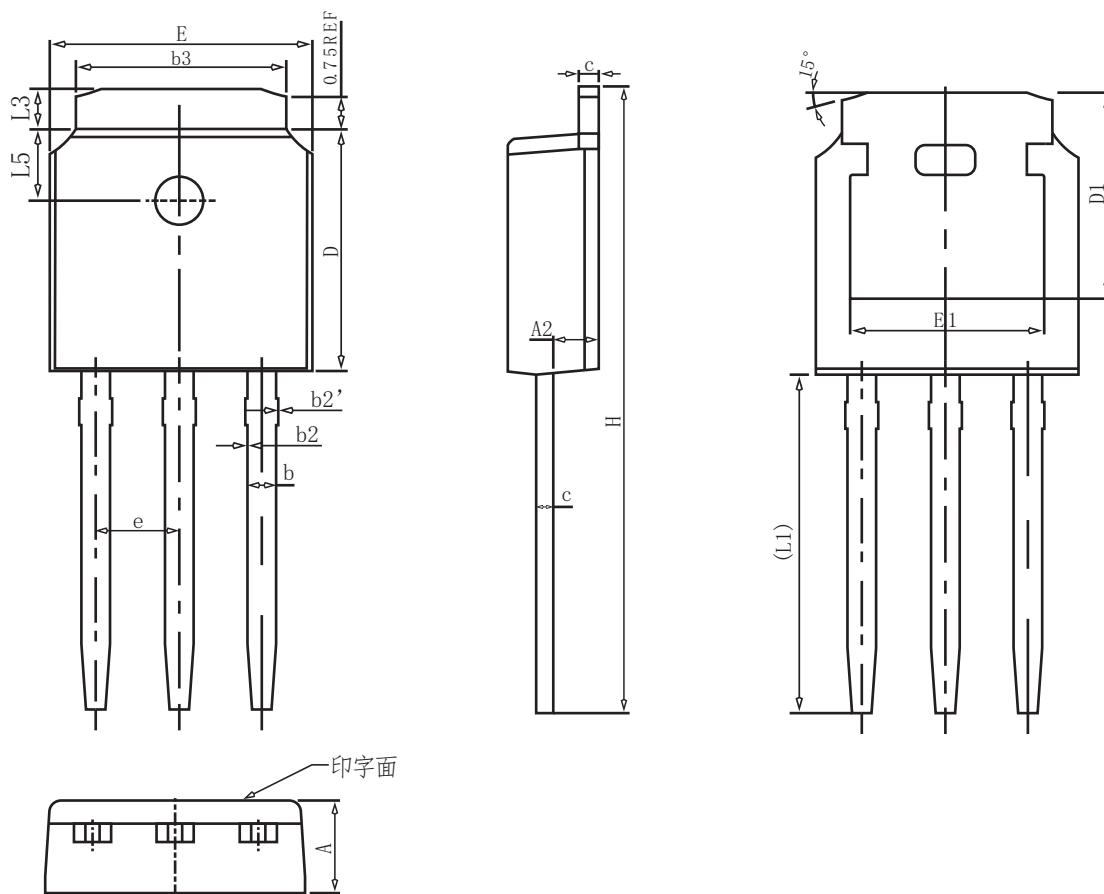


Figure 11. Normalized Maximum Transient Thermal Impedance



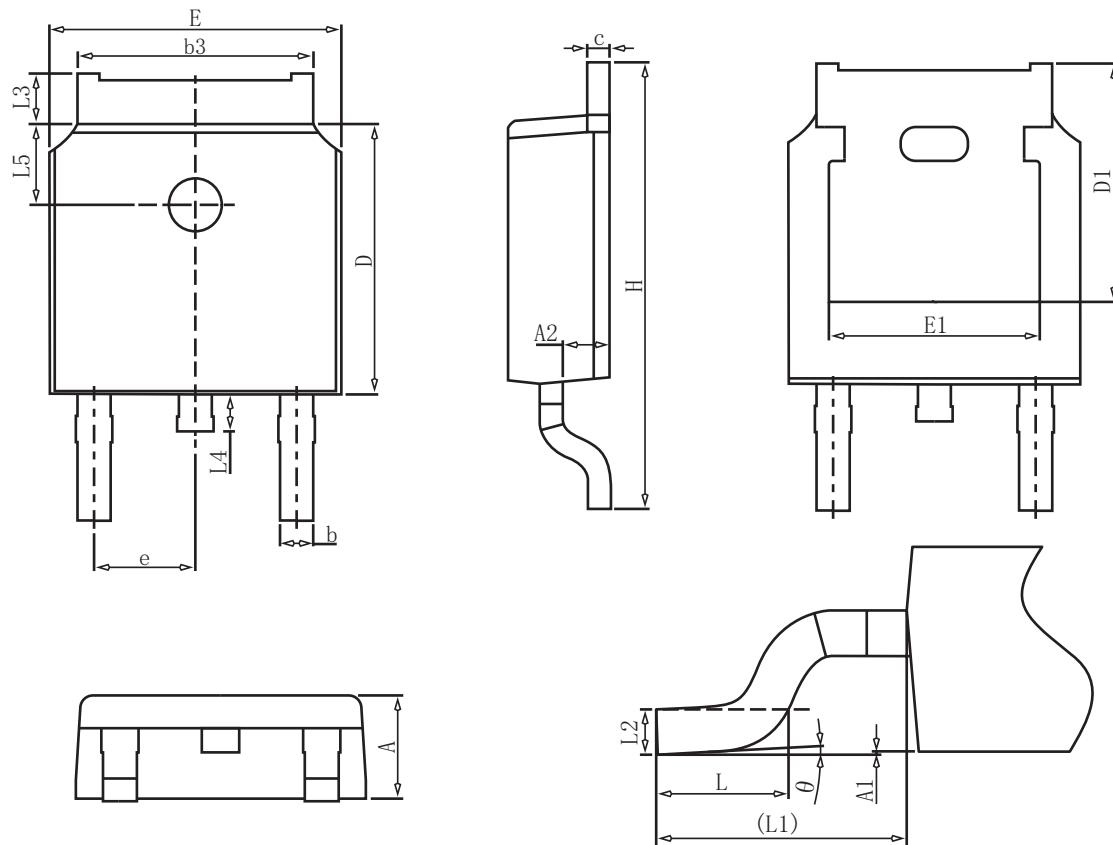
TO-251 package information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1		5.30REF	
E	6.40	6.60	6.80
E1	4.63	-	-
e		2.286BSC	
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

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	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°